
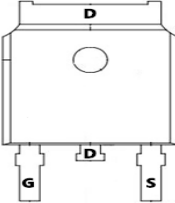
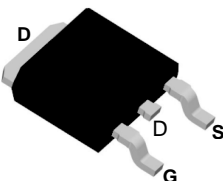
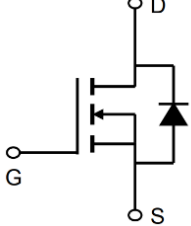


**TMG70N10D**

**N-Channel Enhancement Mosfet**

<p><b>General Description</b></p> <ul style="list-style-type: none"> <li>• Low <math>R_{DS(ON)}</math></li> <li>• RoHS and Halogen-Free Compliant</li> </ul> <p><b>Applications</b></p> <ul style="list-style-type: none"> <li>• Load switch</li> <li>• PWM</li> </ul>	<p><b>General Features</b></p> <p><math>V_{DS} = 100V</math> <math>I_D = 70A</math></p> <p><math>R_{DS(ON)} = 9.5 m\Omega</math>(typ.) @ <math>V_{GS} = 10V</math></p> <p>100% UIS Tested 100% <math>R_g</math> Tested</p> 
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**D:TO-252-3L**

Marking: G70N10

**Absolute Maximum Ratings** ( $T_C = 25^\circ C$  unless otherwise specified)

Symbol	Parameter	Value	Units
$V_{DSS}$	Drain-to-Source Voltage	100	V
$I_D$	Continuous Drain Current	$T_C = 25^\circ C$	70
	Continuous Drain Current	$T_C = 100^\circ C$	45
$I_{DM}^{a1}$	Pulsed Drain Current	259	A
$E_{AS}^{a2}$	Single pulse avalanche energy	110	mJ
$V_{GS}$	Gate-to-Source Voltage	$\pm 20$	V
$P_D$	Power Dissipation	100	W
$T_J, T_{STG}$	Operating Junction and Storage Temperature Range	150, -55 to 150	$^\circ C$
$T_L$	Maximum Temperature for Soldering	260	$^\circ C$

**Thermal Characteristics**

Symbol	Parameter	Value	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	1.25	$^\circ C/W$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	64	$^\circ C/W$



**TMG70N10D**

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**Electrical Characteristics** (TA= 25°C unless otherwise specified):

Static Characteristics						
Symbol	Parameter	Test Conditions	Value			Units
			Min.	Typ.	Max.	
V <sub>DSS</sub>	Drain to Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	100	--	--	V
I <sub>DSS</sub>	Drain to Source Leakage Current	V <sub>DS</sub> =100V, V <sub>GS</sub> =0V	--	--	1	μA
I <sub>GSS(F)</sub>	Gate to Source Forward Leakage	V <sub>GS</sub> =+20V, V <sub>DS</sub> =0V	--	--	100	nA
I <sub>GSS(R)</sub>	Gate to Source Reverse Leakage	V <sub>GS</sub> =-20V, V <sub>DS</sub> =0V	--	--	-100	nA
V <sub>GS(TH)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	1.3	1.8	2.3	V
R <sub>DS(ON)</sub>	Drain-to-Source On-Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =20A	--	9.5	11	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =15A		12	15	mΩ
Dynamic Characteristics						
Symbol	Parameter	Test Conditions	Value			Units
			Min.	Typ.	Max.	
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> = 0V V <sub>DS</sub> = 50V f = 1.0MHz	--	1368	--	pF
C <sub>oss</sub>	Output Capacitance		--	451	--	
C <sub>rss</sub>	Reverse Transfer Capacitance		--	12.9	--	
R <sub>g</sub>	Gate resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> Open	--	0.48	--	Ω
Resistive Switching Characteristics						
Symbol	Parameter	Test Conditions	Value			Units
			Min.	Typ.	Max.	
t <sub>d(ON)</sub>	Turn-on Delay Time	I <sub>D</sub> = 10A V <sub>DS</sub> = 50V V <sub>GS</sub> = 10V R <sub>G</sub> = 4Ω	--	16	--	ns
t <sub>r</sub>	Rise Time		--	10	--	
t <sub>d(OFF)</sub>	Turn-Off Delay Time		--	40	--	
t <sub>f</sub>	Fall Time		--	6	--	
Q <sub>g</sub>	Total Gate Charge	V <sub>GS</sub> = 10V V <sub>DS</sub> = 50V I <sub>D</sub> = 10A	--	31.3	--	nC
Q <sub>gs</sub>	Gate Source Charge		--	3.49	--	
Q <sub>gd</sub>	Gate Drain Charge		--	7.63	--	
Source-Drain Diode Characteristics						
Symbol	Parameter	Test Conditions	Value			Value
			Min.	Typ.	Max.	
I <sub>S</sub>	Diode Forward Current	T <sub>C</sub> = 25 °C	--	--	70	A
V <sub>SD</sub>	Diode Forward Voltage	I <sub>S</sub> =10A, V <sub>GS</sub> =0V	--	--	1.2	V
t <sub>rr</sub>	Reverse Recovery time	I <sub>S</sub> =10A, V <sub>DD</sub> =50V dI/dt=100A/μs	--	103	--	ns
Q <sub>rr</sub>	Reverse Recovery Charge		--	187	--	nC

a1: Repetitive rating; pulse width limited by maximum junction temperature

a2: VDD=50V, L=0.3mH, Rg=25Ω, Starting T<sub>J</sub>=25 °C

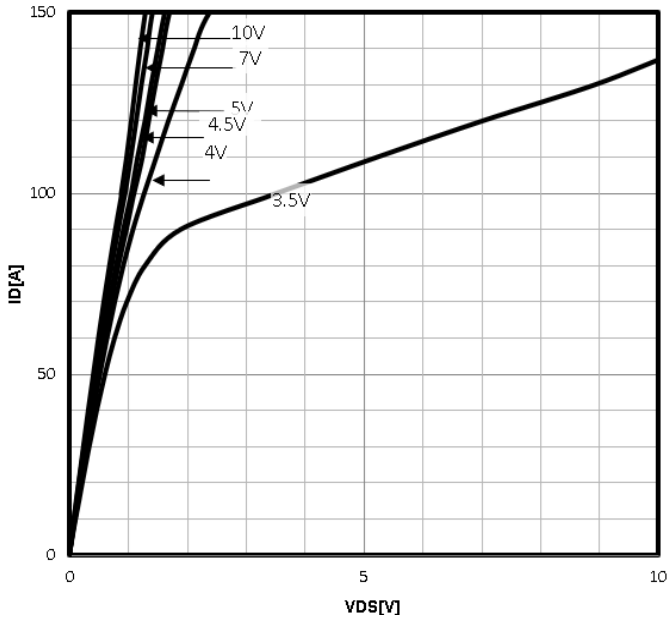


**TMG70N10D**

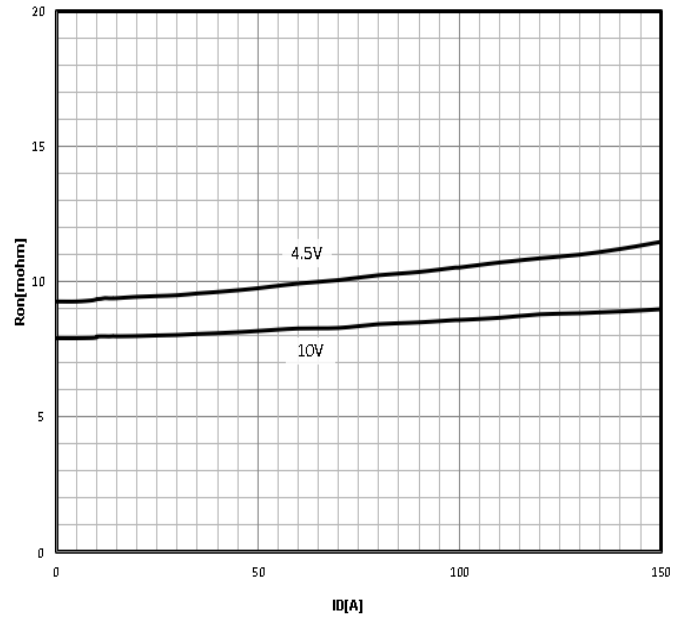
**N-Channel Enhancement Mosfet**

**Characteristics Curve:**

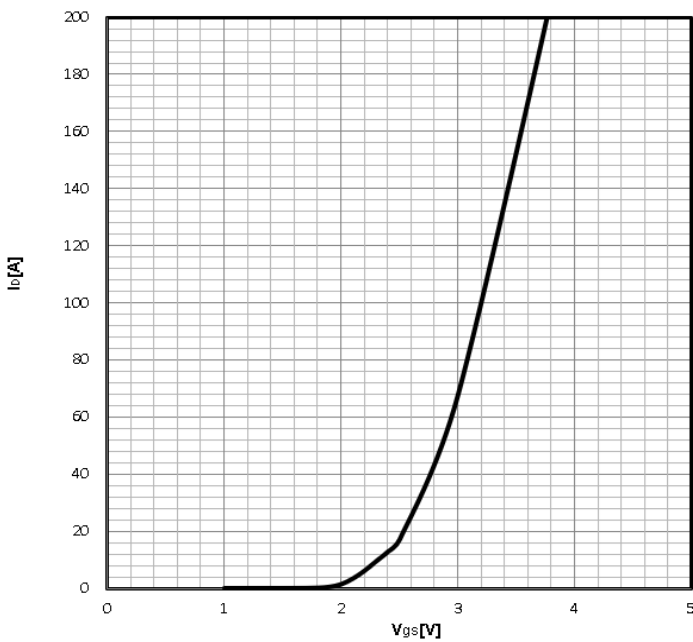
**Typ. output characteristics**  
 $I_D = f(V_{DS})$



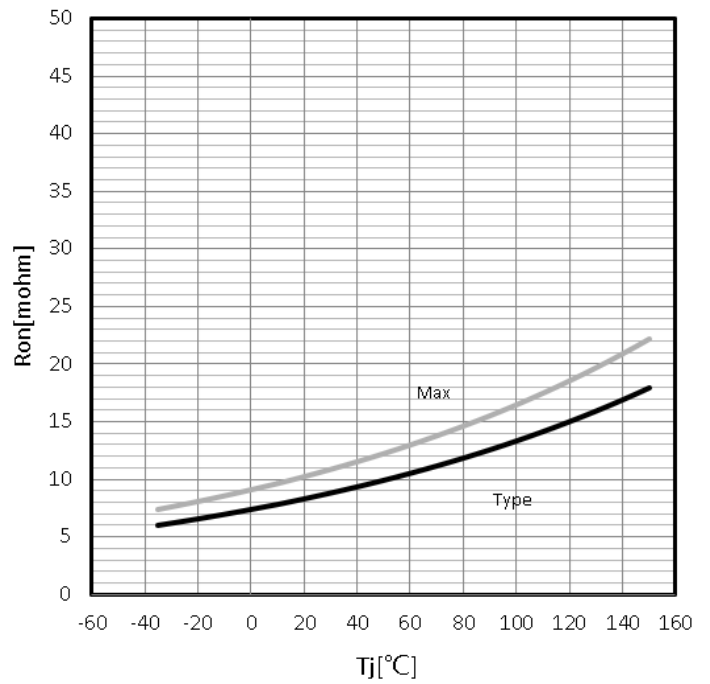
**Typ. drain-source on resistance**  
 $R_{DS(on)} = f(I_D)$



**Typ. transfer characteristics**  
 $I_D = f(V_{GS})$



**Drain-source on-state resistance**  
 $R_{DS(on)} = f(T_j); I_D = 20A; V_{GS} = 10V$



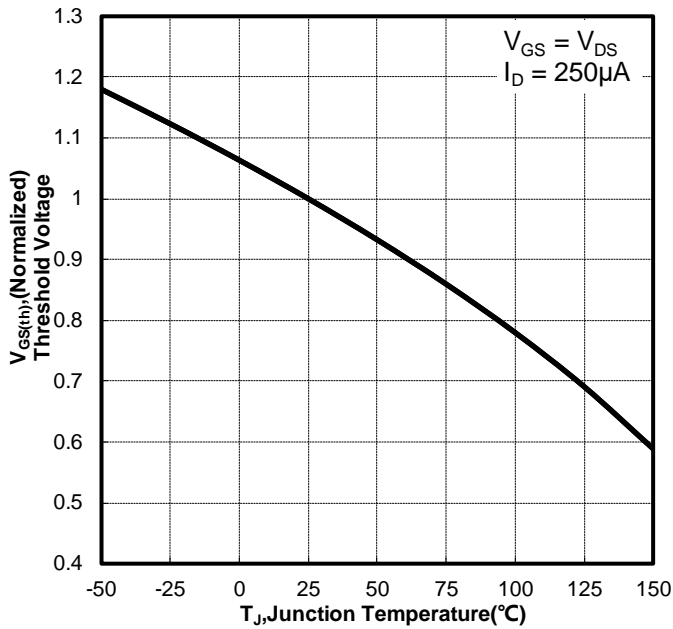


**TMG70N10D**

**N-Channel Enhancement Mosfet**

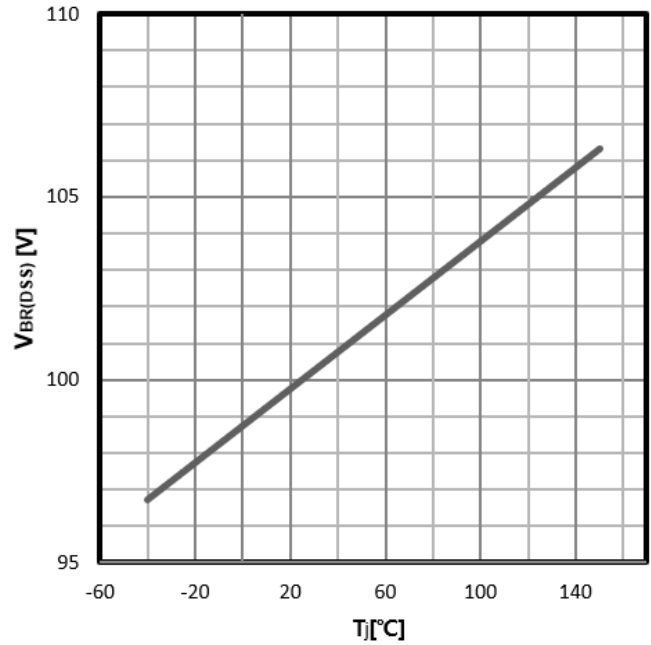
**Gate Threshold Voltage**

$V_{TH}=f(T_j); I_D=250\mu A$



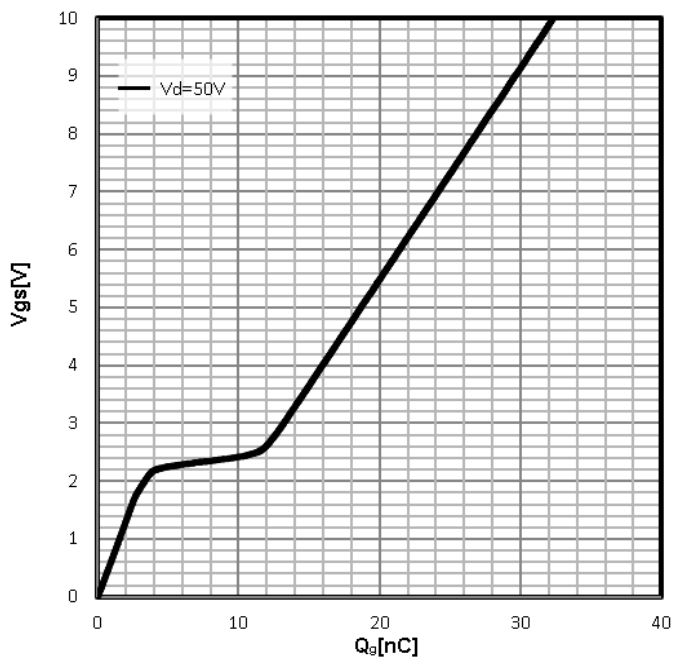
**Drain-source breakdown voltage**

$V_{BR(DSS)}=f(T_j); I_D=250\mu A$



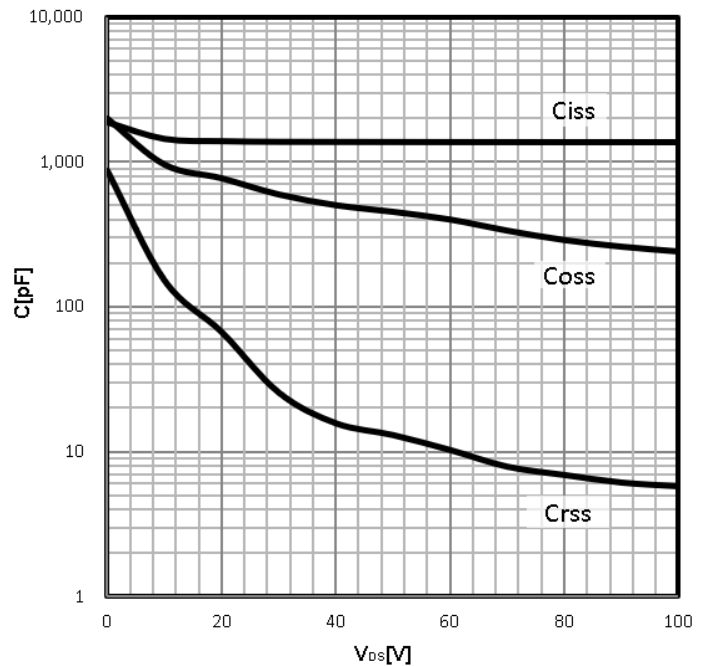
**Typ. gate charge**

$V_{GS}=f(Q_g); I_D=10A$



**Typ. capacitances**

$C=f(V_{DS}); V_{GS}=0V; f=1MHz$



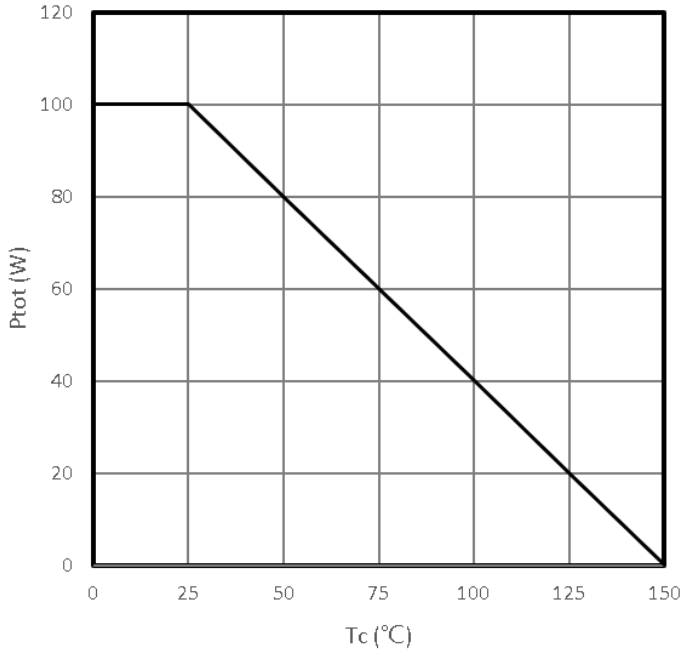


# TMG70N10D

## N-Channel Enhancement Mosfet

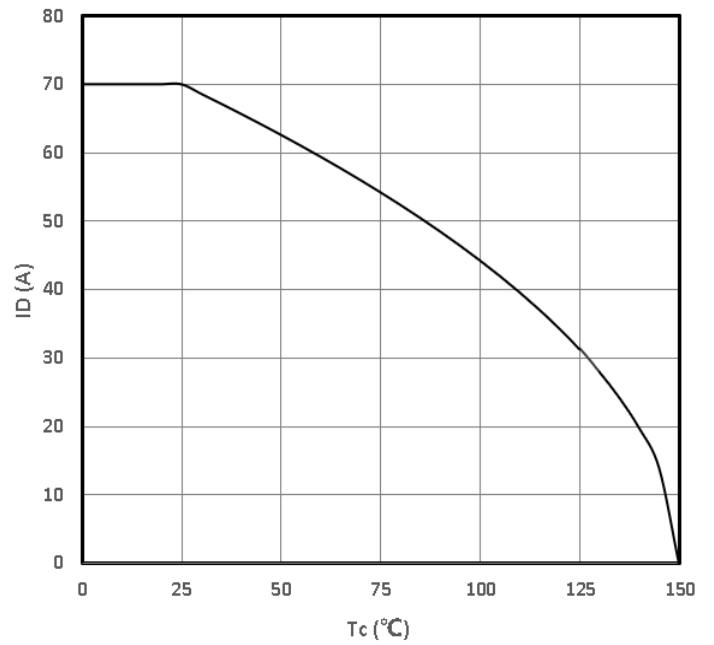
### Power Dissipation

$$P_{tot}=f(T_C)$$



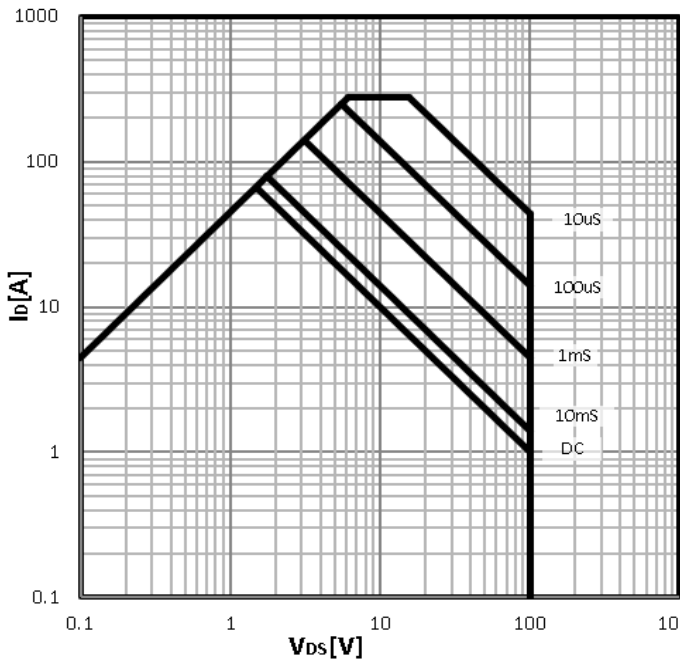
### Maximum Drain Current

$$I_D=f(T_C)$$



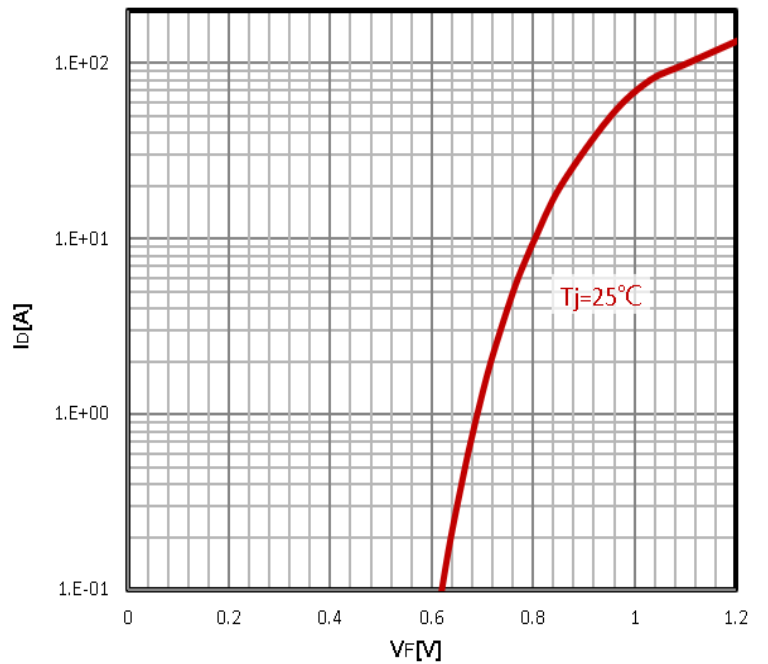
### Safe operating area

$$I_D=f(V_{DS})$$



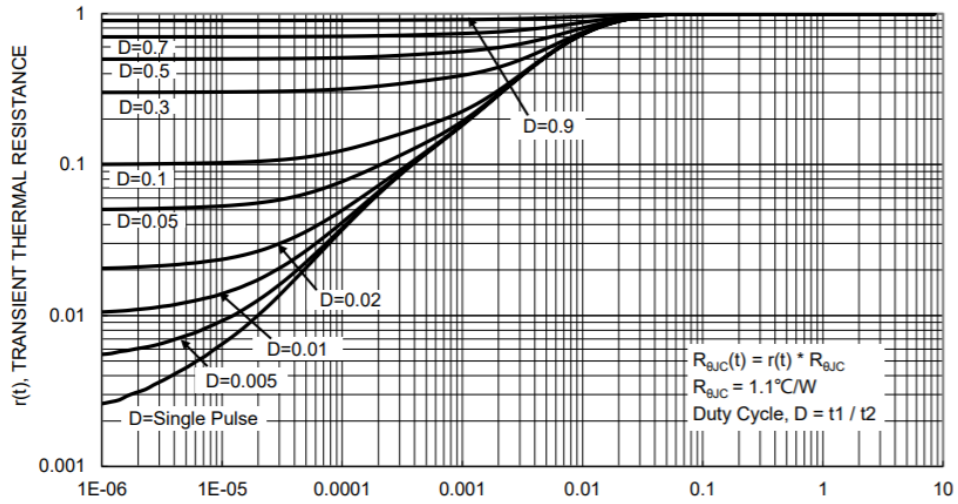
### Body Diode Forward Voltage Variation

$$I_F=f(V_{GS})$$

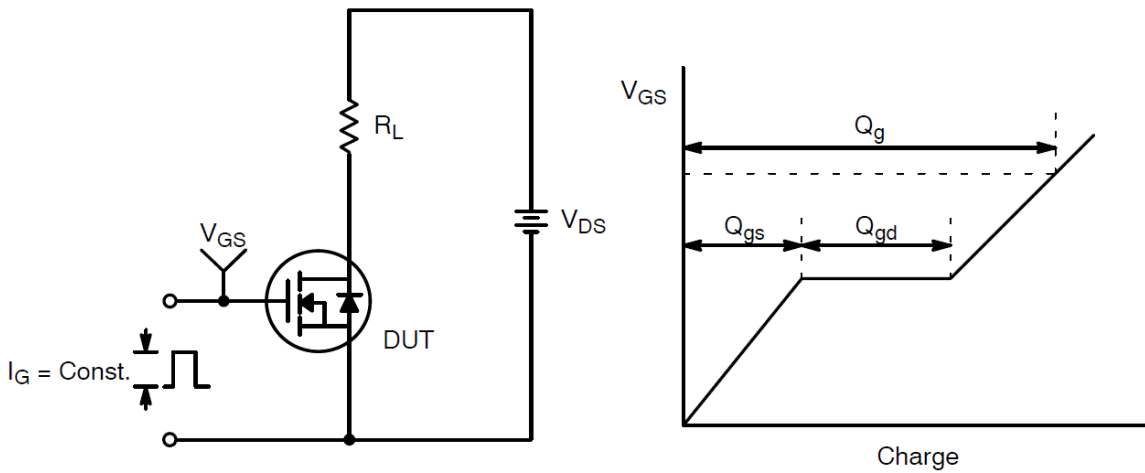


**Max. transient thermal impedance**

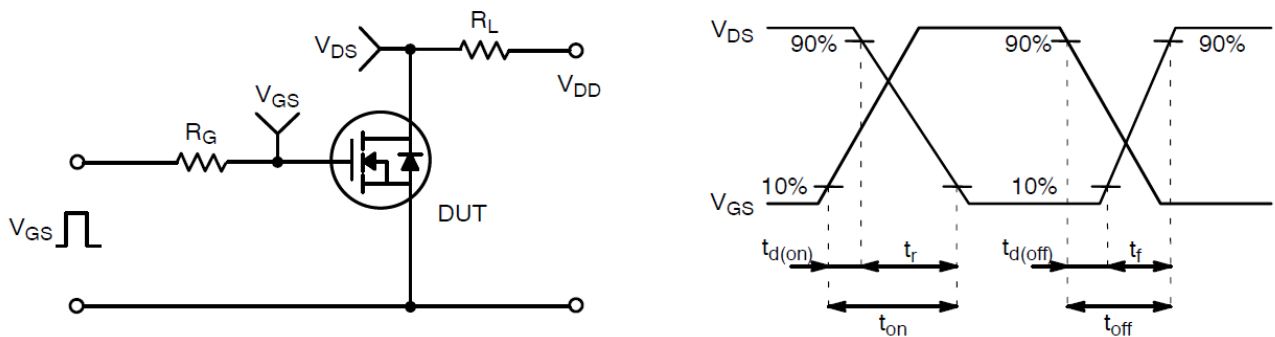
$$Z_{thJC} = f(t_p)$$



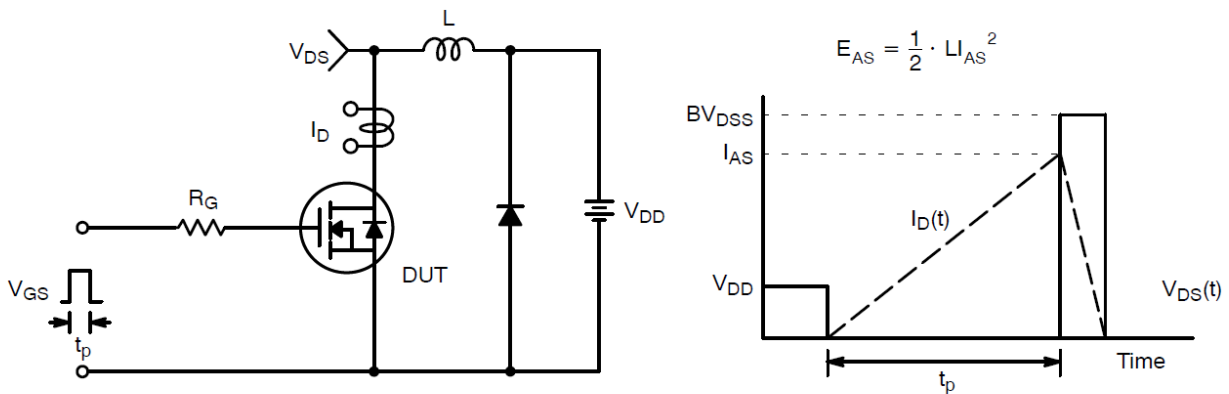
**Test Circuit and Waveform:**



**Gate Charge Test Circuit & Waveform**

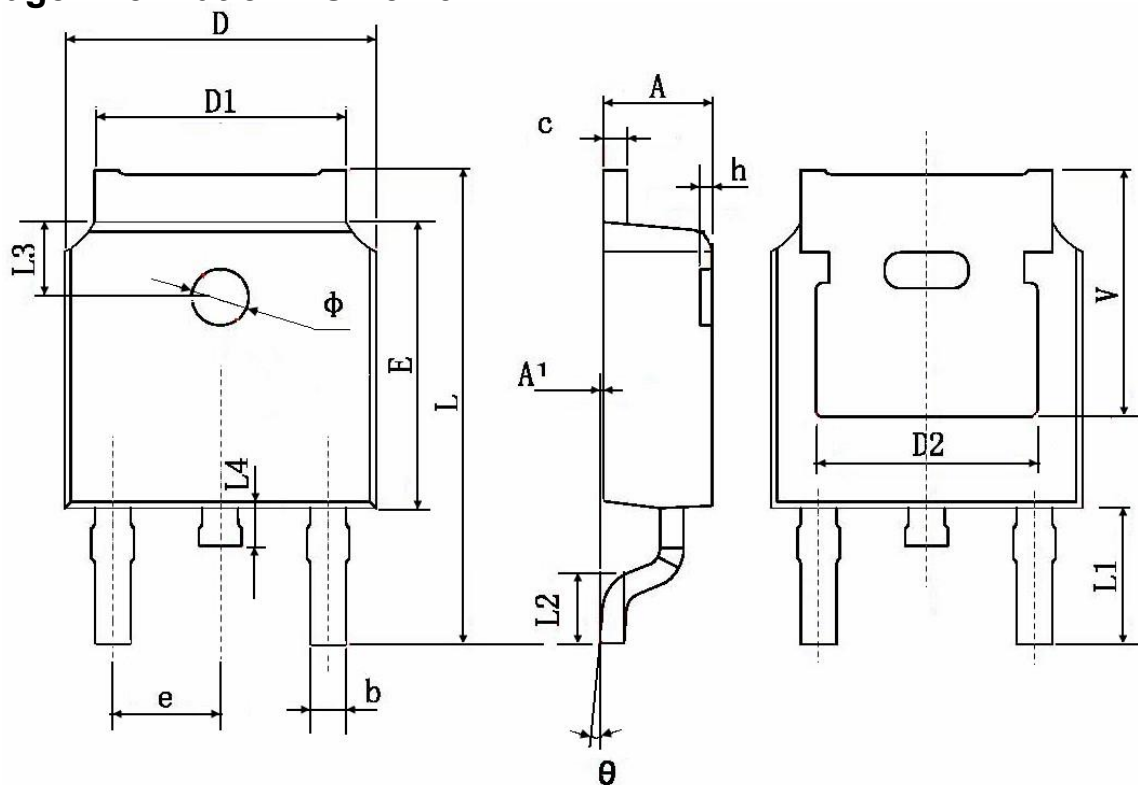


**Resistive Switching Test Circuit & Waveforms**



**Unclamped Inductive Switching Test Circuit & Waveforms**

## Package Information:TO-252-3L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	